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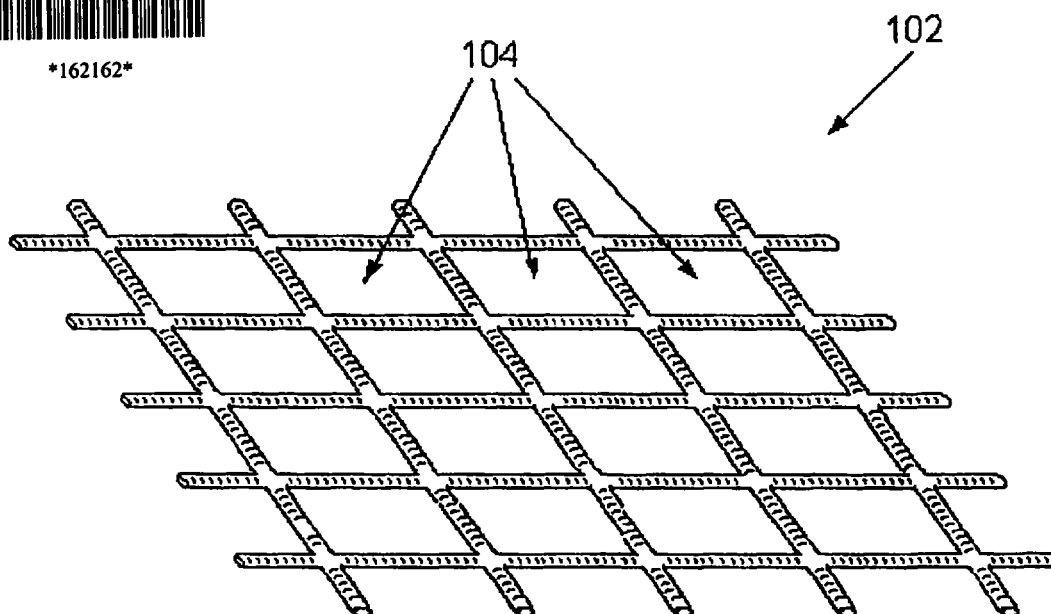
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(54) Title: THERMAL INTERFACE MATERIAL ON A MESH CARRIER



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(57) Abstract: A thermal interface comprising a grid frame having a thermally conductive interface material coated thereon. The thermal interface is disposed between a heat source and a heat dissipation device wherein the thermally conductive material preferably melts at a temperature at or below the temperature of the heat source.



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